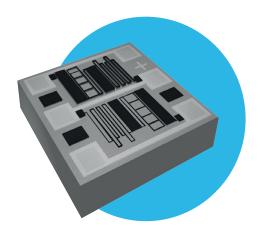
Resistors

Wire Bondable Chip Resistors

WBC Series

- Discrete or tapped schematics
- MIL inspection available
- High resistor density



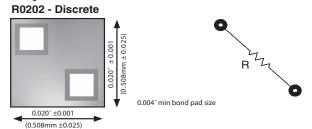


All parts are Pb-free and comply with EU Directive 2011/65/EU amended by (EU) 2015/863 (RoHS3)

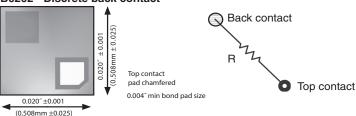
The WBC combines IRC's TaNSil® tantalum nitride thin film technology with silicon substrate processing to produce an extremely small tantalum nitride thin film technology with silicon substrate processing to produce an extremely small footprint device with the proven stability, reliability and moisture performance of IRC's TaNSil® resistor film.

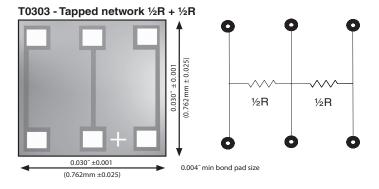
Available in a wide range of tolerances and temperature coefficients to fit a variety of hybrid circuit applications. Custom resistance values, sizes and schematics are available on request from the factory.

Physical Data



B0202 - Discrete back contact1





Electrical Data

Absolute Tolerance		to ±0.1%		
Absolute TCR		to ±25ppm/°C		
Package Power Rating (@ 70°C)		250mW		
Rated Operating Voltage (not to exceed √P x R)		100V		
Operating Temperature		-55°C to +150°C		
Noise		<-30dB		
Substrate Material		Oxidized Silicon (10KÅ SiO ₂ min)		
Substrate Thickness		0.010" ±0.001 (0.254mm ±0.025)		
Bond Pad Metallization	Aluminum	10KÅ minimum		
	Gold ¹	15KÅ minimum		
Backside	R0202 and T0303	Silicon (Al / Au optional)		
	B0202 ¹	3KÅ Au minimum 10KÅ Al minimum		
Passivation		Silicon Dioxide or Silicon Nitride		

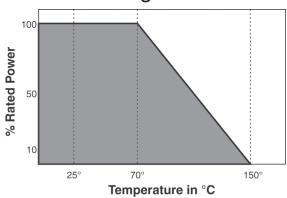
Note 1: Not recommended for new designs

General Note

WBC Series



Power Derating Data



TCR/Inspection Code Table

Absolute TCR	Commercial Code	MIL Inspection Code*	
±300ppm/°C	00	04	
±100ppm/°C	01	05	
±50ppm/°C	02	06	
±25ppm/°C	03	07	

*Notes: Product supplied to Class H of MIL-PRF 38534 includes 100% visual inspection

Manufacturing Capabilities Data

Resistance Range	Package	Available Abs Tolerances	Available Ratio Tol (T0303 only)	Best Absolute TCR	Tracking TCR (T0303 only)
10Ω - 20Ω	0202 only	GJK	N/A	+-100ppm/C	N/A
21Ω - 50Ω	0202 and 0303	FGJK	FGJ	+-100ppm/C	+-50ppm/C
51Ω - 100Ω	0202 and 0303	CDFGJK	CDFGJ	+-100ppm/C	+-25ppm/C
101Ω - 200Ω	0202 and 0303	CDFGJK	CDFGJ	+-50ppm/C	+-10ppm/C
201Ω - 500Ω	0202 and 0303	BCDFGJK	BCDFGJ	+-50ppm/C	+-5ppm/C
501Ω - 999Ω	0202 and 0303	BCDFGJK	BCDFGJ	+-25ppm/C	+-2ppm/C
1.0ΚΩ - 400ΚΩ	0202 and 0303	BCDFGJK	A B C D F G J	+-25ppm/C	+-2ppm/C
401ΚΩ - 800ΚΩ	0303 only	BCDFGJK	ABCDFGJ	+-25ppm/C	+-2ppm/C

Wire Bondable **Chip Resistors**

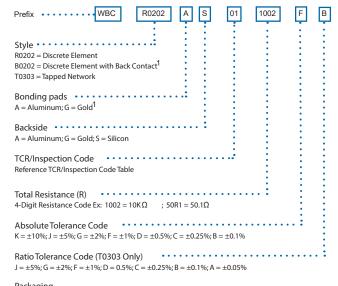




Environmental Data

Test	Method	Max R	Typical R
Thermal Shock	MIL-STD-202 Method 107 Test condition F	±0.1%	±0.02%
High Temperature Exposure	MIL-STD-883 Method 1008 150°C, 1000 hours	±0.1%	±0.05%
LowTemperature Storage	-55°C, 1000 hours	±0.03%	±0.01%
Life	MIL-STD-202 Method 108 70°C, 1000 hours	±0.5%	±0.01%
Life at Elevated Temperature	MIL-STD-202 Method 108 125°C, 1000 hours	±0.5%	±0.05%

Ordering Data



Standard packaging is 2" x 2" chip tray. For additional information or to discuss your specific requirements, please contact our Applications Team using the contact details below.

Note 1: Not recommended for new designs